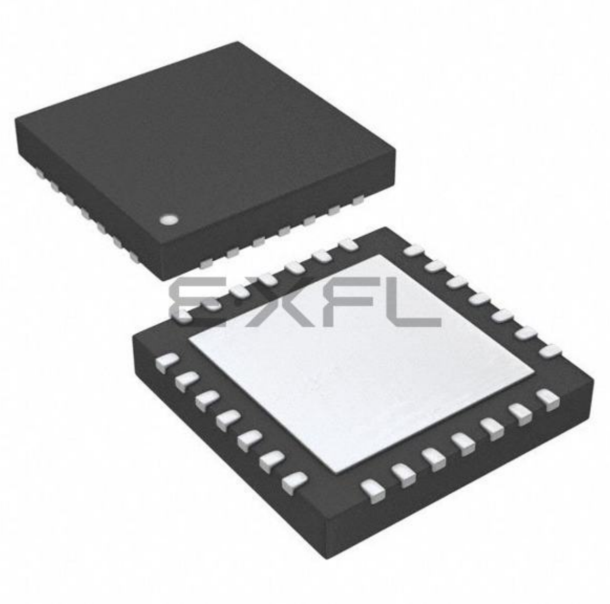


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

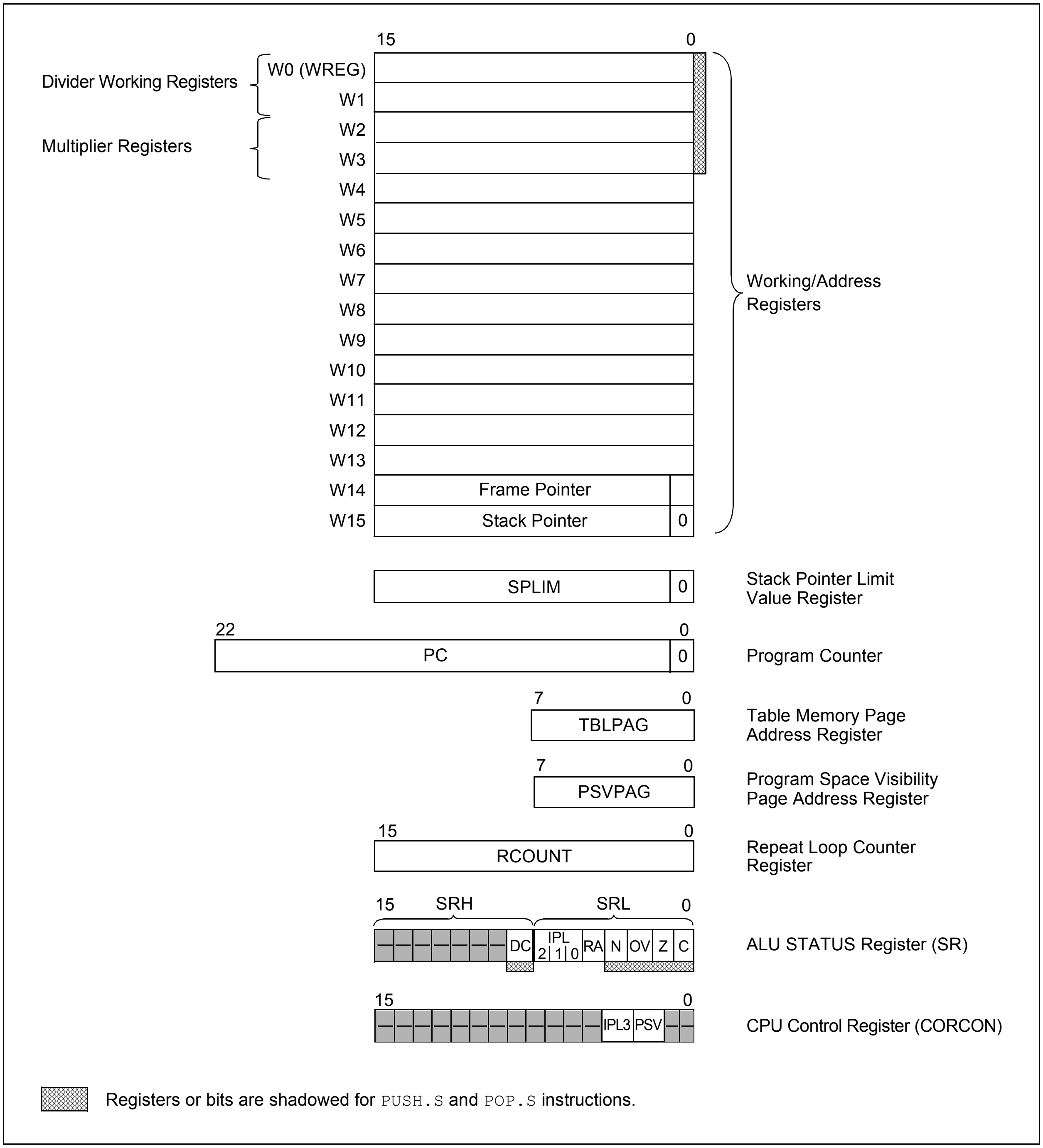
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv32ka302t-i-ml

TABLE 1-3: PIC24FV32KA304 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	F					FV					I/O	Buffer	Description
	Pin Number					Pin Number							
	20-Pin PDIP/ SSOP/ SOIC	28-Pin SPDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin SPDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN			
C3INA	18	26	23	15	16	18	26	23	15	16	I	ANA	Comparator 3 Input A (+)
C3INB	17	25	22	14	15	17	25	22	14	15	I	ANA	Comparator 3 Input B (-)
C3INC	2	2	27	19	21	2	2	27	19	21	I	ANA	Comparator 3 Input C (+)
C3IND	4	4	1	21	23	4	4	1	21	23	I	ANA	Comparator 3 Input D (-)
C3OUT	12	17	14	44	48	12	17	14	44	48	O	—	Comparator 3 Output
CLK I	7	9	6	30	33	7	9	6	30	33	I	ANA	Main Clock Input
CLKO	8	10	7	31	34	8	10	7	31	34	O	—	System Clock Output
CN0	10	12	9	34	37	10	12	9	34	37	I	ST	Interrupt-on-Change Inputs
CN1	9	11	8	33	36	9	11	8	33	36	I	ST	
CN2	2	2	27	19	21	2	2	27	19	21	I	ST	
CN3	3	3	28	20	22	3	3	28	20	22	I	ST	
CN4	4	4	1	21	23	4	4	1	21	23	I	ST	
CN5	5	5	2	22	24	5	5	2	22	24	I	ST	
CN6	6	6	3	23	25	6	6	3	23	25	I	ST	
CN7	—	7	4	24	26	—	7	4	24	26	I	ST	
CN8	14	20	17	7	7	—	—	—	—	—	I	ST	
CN9	—	19	16	6	6	—	19	16	6	6	I	ST	
CN10	—	—	—	27	29	—	—	—	27	29	I	ST	
CN11	18	26	23	15	16	18	26	23	15	16	I	ST	
CN12	17	25	22	14	15	17	25	22	14	15	I	ST	
CN13	16	24	21	11	12	16	24	21	11	12	I	ST	
CN14	15	23	20	10	11	15	23	20	10	11	I	ST	
CN15	—	22	19	9	10	—	22	19	9	10	I	ST	
CN16	—	21	18	8	9	—	21	18	8	9	I	ST	
CN17	—	—	—	3	3	—	—	—	3	3	I	ST	
CN18	—	—	—	2	2	—	—	—	2	2	I	ST	
CN19	—	—	—	5	5	—	—	—	5	5	I	ST	
CN20	—	—	—	4	4	—	—	—	4	4	I	ST	
CN21	13	18	15	1	1	13	18	15	1	1	I	ST	
CN22	12	17	14	44	48	12	17	14	44	48	I	ST	

FIGURE 3-2: PROGRAMMER'S MODEL

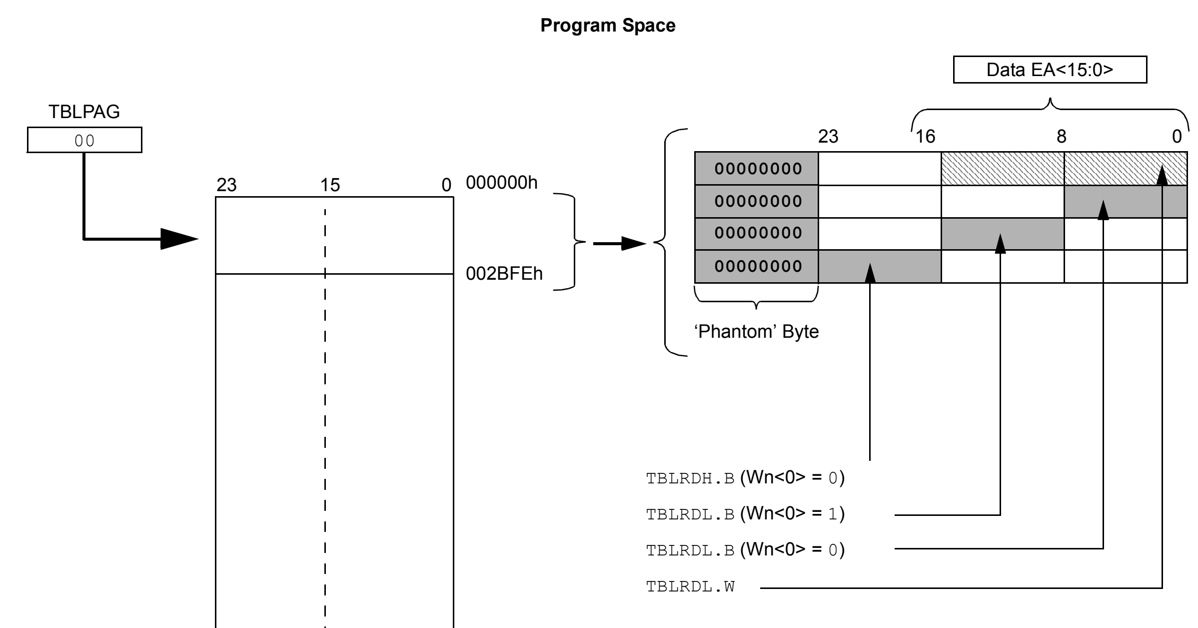


In a similar fashion, two table instructions, `TBLWTH` and `TBLWTL`, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Memory Page Address register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = `0`, the table page is located in the user memory space. When TBLPAG<7> = `1`, the page is located in configuration space.

> **Note:** Only Table Read operations will execute in the configuration memory space, and only then, in implemented areas, such as the Device ID. Table write operations are not allowed.

FIGURE 4-6: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



The address for the table operation is determined by the data EA within the page defined by the TBLPAG register. Only read operations are provided; write operations are also valid in the user memory area.

6.4.1 ERASE DATA EEPROM

The data EEPROM can be fully erased, or can be partially erased, at three different sizes: one word, four words or eight words. The bits, NVMOP<1:0> (NVMCON<1:0>), decide the number of words to be erased. To erase partially from the data EEPROM, the following sequence must be followed:

1. Configure NVMCON to erase the required number of words: one, four or eight.
2. Load TBLPAG and WREG with the EEPROM address to be erased.
3. Clear the NVMIF status bit and enable the NVM interrupt (optional).
4. Write the key sequence to NVMKEY.
5. Set the WR bit to begin the erase cycle.
6. Either poll the WR bit or wait for the NVM interrupt (NVMIF is set).

A typical erase sequence is provided in Example 6-2. This example shows how to do a one-word erase. Similarly, a four-word erase and an eight-word erase can be done. This example uses C library procedures to manage the Table Pointer (`builtin_tblpage` and `builtin_tbloffset`) and the Erase Page Pointer (`builtin_tblwtl`). The memory unlock sequence (`builtin_write_NVM`) also sets the WR bit to initiate the operation and returns control when complete.

EXAMPLE 6-2: SINGLE-WORD ERASE

```
int __attribute__ ((space(eedata))) eeData = 0x1234;
/*-------------------------------------------------------------------------------------------------
The variable eeData must be a Global variable declared outside of any method

the code following this comment can be written inside the method that will execute the erase
---------------------------------------------------------------------------------------------------
*/
    unsigned int offset;

    // Set up NVMCON to erase one word of data EEPROM
    NVMCON = 0x4058;

    // Set up a pointer to the EEPROM location to be erased
    TBLPAG = __builtin_tblpage(&eeData);            // Initialize EE Data page pointer
    offset = __builtin_tbloffset(&eeData);          // Initizlize lower word of address
    __builtin_tblwtl(offset, 0);                    // Write EEPROM data to write latch

    asm volatile ("disi #5");                       // Disable Interrupts For 5 Instructions
    __builtin_write_NVM();                          // Issue Unlock Sequence & Start Write Cycle
    while(NVMCONbits.WR=1);                         // Optional: Poll WR bit to wait for
                                                    // write sequence to complete
```


REGISTER 8-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
NSTDIS	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-0, HS	U-0
—	—	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14-5 **Unimplemented:** Read as ‘0’

bit 4 **MATHERR:** Arithmetic Error Trap Status bit
1 = Overflow trap has occurred
0 = Overflow trap has not occurred

bit 3 **ADDRERR:** Address Error Trap Status bit
1 = Address error trap has occurred
0 = Address error trap has not occurred

bit 2 **STKERR:** Stack Error Trap Status bit
1 = Stack error trap has occurred
0 = Stack error trap has not occurred

bit 1 **OSCFAIL:** Oscillator Failure Trap Status bit
1 = Oscillator failure trap has occurred
0 = Oscillator failure trap has not occurred

bit 0 **Unimplemented:** Read as ‘0’

10.2.2 IDLE MODE

Idle mode has these features:

- The CPU will stop executing instructions.
- The WDT is automatically cleared.
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 10.6 "Selective Peripheral Module Control"**).
- If the WDT or FSCM is enabled, the LPRC will also remain active.

The device will wake from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle, the clock is re-applied to the CPU and instruction execution begins immediately, starting with the instruction following the `PWRSAV` instruction or the first instruction in the ISR.

10.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a `PWRSAV` instruction will be held off until entry into Sleep or Idle mode has completed. The device will then wake-up from Sleep or Idle mode.

10.2.4 DEEP SLEEP MODE

In PIC24FV32KA304 family devices, Deep Sleep mode is intended to provide the lowest levels of power consumption available without requiring the use of external switches to completely remove all power from the device. Entry into Deep Sleep mode is completely under software control. Exit from Deep Sleep mode can be triggered from any of the following events:

- POR Event
- $\overline{\text{MCLR}}$ Event
- RTCC Alarm (if the RTCC is present)
- External Interrupt 0
- Deep Sleep Watchdog Timer (DSWDT) Time-out
- Ultra Low-Power Wake-up (ULPWU) Event

In Deep Sleep mode, it is possible to keep the device Real-Time Clock and Calendar (RTCC) running without the loss of clock cycles.

The device has a dedicated Deep Sleep Brown-out Reset (DSBOR) and a Deep Sleep Watchdog Timer Reset (DSWDT) for monitoring voltage and time-out events. The DSBOR and DSWDT are independent of the standard BOR and WDT used with other power-managed modes (Sleep, Idle and Doze).

10.2.4.1 Entering Deep Sleep Mode

Deep Sleep mode is entered by setting the DSEN bit in the DSCON register and then executing a Sleep command (`PWRSAV #SLEEP_MODE`). An unlock sequence is required to set the DSEN bit. Once the DSEN bit has been set, there is no time limit before the `SLEEP` command can be executed. The DSEN bit is automatically cleared when exiting the Deep Sleep mode.

Note:	To re-enter Deep Sleep after a Deep Sleep wake-up, allow a delay of at least 3 T_{CY} after clearing the RELEASE bit.

The sequence to enter Deep Sleep mode is:

1. If the application requires the Deep Sleep WDT, enable it and configure its clock source. For more information on Deep Sleep WDT, see **Section 10.2.4.5 "Deep Sleep WDT"**.
2. If the application requires Deep Sleep BOR, enable it by programming the DSLPBOR Configuration bit (FDS<6>).
3. If the application requires wake-up from Deep Sleep on RTCC alarm, enable and configure the RTCC module For more information on RTCC, see **Section 19.0 "Real-Time Clock and Calendar (RTCC)"**.
4. If needed, save any critical application context data by writing it to the DSGPR0 and DSGPR1 registers (optional).
5. Enable Deep Sleep mode by setting the DSEN bit (DSCON<15>).

Note:	An unlock sequence is required to set the DSEN bit.

6. Enter Deep Sleep mode by issuing a `PWRSAV #0` instruction.

Any time the DSEN bit is set, all bits in the DSWAKE register will be automatically cleared.

To set the DSEN bit, the unlock sequence in Example 10-2 is required:

EXAMPLE 10-2: THE UNLOCK SEQUENCE

```
//Disable Interrupts For 5 instructions
asm   volatile("disi #5");
//Issue Unlock Sequence
asm   volatile
mov   #0x55, W0;
mov   W0, NVMKEY;
mov   #0xAA, W1;
mov   W1, NVMKEY;
bset  DSCON, #DSEN
```


REGISTER 18-2: UxSTA: UARTx STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	R/W-0, HC	R/W-0	R-0, HSC	R-1, HSC
UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN	UTXBF	TRMT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-1, HSC	R-0, HSC	R-0, HSC	R/C-0, HS	R-0, HSC
URXISEL1	URXISEL0	ADDEN	RIDLE	PERR	FERR	OERR	URXDA
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
HS = Hardware Settable bit	C = Clearable bit	HSC = Hardware Settable/Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15,13 **UTXISEL<1:0>:** UARTx Transmission Interrupt Mode Selection bits

- 11 = Reserved; do not use
- 10 = Interrupt when a character is transferred to the Transmit Shift Register (TSR) and as a result, the transmit buffer becomes empty
- 01 = Interrupt when the last character is shifted out of the Transmit Shift Register; all transmit operations are completed
- 00 = Interrupt when a character is transferred to the Transmit Shift Register (this implies there is at least one character open in the transmit buffer)

bit 14 **UTXINV:** IrDA® Encoder Transmit Polarity Inversion bit

If IREN = 0:
1 = UxTX Idle '0'
0 = UxTX Idle '1'

If IREN = 1:
1 = UxTX Idle '1'
0 = UxTX Idle '0'

bit 12 **Unimplemented:** Read as '0'

bit 11 **UTXBRK:** UARTx Transmit Break bit

- 1 = Sends Sync Break on next transmission – Start bit, followed by twelve '0' bits, followed by Stop bit; cleared by hardware upon completion
- 0 = Sync Break transmission is disabled or completed

bit 10 **UTXEN:** UARTx Transmit Enable bit

- 1 = Transmit is enabled; UxTX pin is controlled by UARTx
- 0 = Transmit is disabled; any pending transmission is aborted and the buffer is reset. UxTX pin is controlled by the PORT register.

bit 9 **UTXBF:** UARTx Transmit Buffer Full Status bit (read-only)

- 1 = Transmit buffer is full
- 0 = Transmit buffer is not full, at least one more character can be written

bit 8 **TRMT:** Transmit Shift Register Empty bit (read-only)

- 1 = Transmit Shift Register is empty and the transmit buffer is empty (the last transmission has completed)
- 0 = Transmit Shift Register is not empty; a transmission is in progress or queued

bit 7-6 **URXISEL<1:0>:** UARTx Receive Interrupt Mode Selection bits

- 11 = Interrupt is set on a RSR transfer, making the receive buffer full (i.e., has 4 data characters)
- 10 = Interrupt is set on a RSR transfer, making the receive buffer 3/4 full (i.e., has 3 data characters)
- 0x = Interrupt is set when any character is received and transferred from the RSR to the receive buffer; receive buffer has one or more characters.

REGISTER 18-2: UxSTA: UARTx STATUS AND CONTROL REGISTER (CONTINUED)

bit 5	**ADDEN:** Address Character Detect bit (bit 8 of received data = 1) 1 = Address Detect mode is enabled; if 9-bit mode is not selected, this does not take effect 0 = Address Detect mode is disabled
bit 4	**RIDLE:** Receiver Idle bit (read-only) 1 = Receiver is Idle 0 = Receiver is active
bit 3	**PERR:** Parity Error Status bit (read-only) 1 = Parity error has been detected for the current character (character at the top of the receive FIFO) 0 = Parity error has not been detected
bit 2	**FERR:** Framing Error Status bit (read-only) 1 = Framing error has been detected for the current character (character at the top of the receive FIFO) 0 = Framing error has not been detected
bit 1	**OERR:** Receive Buffer Overrun Error Status bit (clear/read-only) 1 = Receive buffer has overflowed 0 = Receive buffer has not overflowed (clearing a previously set OERR bit (1 → 0 transition) will reset the receiver buffer and the RSR to the empty state)
bit 0	**URXDA:** UARTx Receive Buffer Data Available bit (read-only) 1 = Receive buffer has data; at least one more characters can be read 0 = Receive buffer is empty

19.2.4 RTCC CONTROL REGISTERS

REGISTER 19-1: RCFGCAL: RTCC CALIBRATION AND CONFIGURATION REGISTER(1)

R/W-0	U-0	R/W-0	R-0, HSC	R-0, HSC	R/W-0	R/W-0	R/W-0
RTCEN(2)	—	RTCWREN	RTCSYNC	HALFSEC(3)	RTCOE	RTCPTR1	RTCPTR0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CAL7	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **RTCEN:** RTCC Enable bit(2)
1 = RTCC module is enabled
0 = RTCC module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **RTCWREN:** RTCC Value Registers Write Enable bit
1 = RTCVALH and RTCVALL registers can be written to by the user
0 = RTCVALH and RTCVALL registers are locked out from being written to by the user

bit 12 **RTCSYNC:** RTCC Value Registers Read Synchronization bit
1 = RTCVALH, RTCVALL and ALCFGRPT registers can change while reading due to a rollover ripple resulting in an invalid data read. If the register is read twice and results in the same data, the data can be assumed to be valid.
0 = RTCVALH, RTCVALL or ALCFGRPT registers can be read without concern over a rollover ripple

bit 11 **HALFSEC:** Half Second Status bit(3)
1 = Second half period of a second
0 = First half period of a second

bit 10 **RTCOE:** RTCC Output Enable bit
1 = RTCC output is enabled
0 = RTCC output is disabled

bit 9-8 **RTCPTR<1:0>:** RTCC Value Register Window Pointer bits
Points to the corresponding RTCC Value registers when reading the RTCVALH and RTCVALL registers. The RTCPTR<1:0> value decrements on every read or write of RTCVALH until it reaches ‘00’.

RTCVAL<15:8>:
00 = MINUTES
01 = WEEKDAY
10 = MONTH
11 = Reserved

RTCVAL<7:0>:
00 = SECONDS
01 = HOURS
10 = DAY
11 = YEAR

Note 1: The RCFGCAL register is only affected by a POR.
2: A write to the RTCEN bit is only allowed when RTCWREN = 1.
3: This bit is read-only; it is cleared to ‘0’ on a write to the lower half of the MINSEC register.

To perform an A/D conversion:

1. Configure the A/D module:
   a) Configure the port pins as analog inputs and/or select band gap reference inputs (ANS<12:10>, ANS<5:0>).
   b) Select voltage reference source to match the expected range on the analog inputs (AD1CON2<15:13>).
   c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
   d) Select the appropriate sample/conversion sequence (AD1CON1<7:4> and AD1CON3<12:8>).
   e) Select how conversion results are presented in the buffer (AD1CON1<9:8>).
   f) Select the interrupt rate (AD1CON2<6:2>).
   g) Turn on the A/D module (AD1CON1<15>).
2. Configure the A/D interrupt (if required):
   a) Clear the AD1IF bit.
   b) Select the A/D interrupt priority.

To perform an A/D sample and conversion using Threshold Detect scanning:

1. Configure the A/D module:
   a) Configure the port pins as analog inputs (ANS<12:10>, ANS<5,0>).
   b) Select the voltage reference source to match the expected range on the analog inputs (AD1CON2<15:13>).
   c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
   d) Select the appropriate sample/conversion sequence (AD1CON1<7:4>, AD1CON3<12:8>).
   e) Select how the conversion results are presented in the buffer (AD1CON1<9:8>).
   f) Select the interrupt rate (AD1CON2<6:2>).
2. Configure the threshold compare channels:
   a) Enable auto-scan – ASEN bit (AD1CON5<15>).
   b) Select the Compare mode, “Greater Than, Less Than or Windowed” – CMx bits (AD1CON5<1:0>).
   c) Select the threshold compare channels to be scanned (ADCSSH, ADCSSL).
   d) If the CTMU is required as a current source for a threshold compare channel, enable the corresponding CTMU channel (ADCCTMUENH, ADCCTMUENL).
   e) Write the threshold values into the corresponding ADC1BUFn registers.
   f) Turn on the A/D module (AD1CON1<15>).

Note:	If performing an A/D sample and conversion using Threshold Detect in Sleep Mode, the RC A/D clock source must be selected before entering into Sleep mode.

3. Configure the A/D interrupt (OPTIONAL):
   a) Clear the AD1IF bit.
   b) Select the A/D interrupt priority.

REGISTER 23-1: CMxCON: COMPARATOR x CONTROL REGISTERS

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R-0
CON	COE	CPOL	CLPWR	—	—	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Comparator x Enable bit
1 = Comparator is enabled
0 = Comparator is disabled

bit 14 **COE:** Comparator x Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator x Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12 **CLPWR:** Comparator x Low-Power Mode Select bit
1 = Comparator operates in Low-Power mode
0 = Comparator does not operate in Low-Power mode

bit 11-10 **Unimplemented:** Read as ‘0’

bit 9 **CEVT:** Comparator x Event bit
1 = Comparator event defined by EVPOL<1:0> has occurred; subsequent triggers and interrupts are disabled until the bit is cleared
0 = Comparator event has not occurred

bit 8 **COUT:** Comparator x Output bit
When CPOL = 0:
1 = $V_{IN+} > V_{IN-}$
0 = $V_{IN+} < V_{IN-}$
When CPOL = 1:
1 = $V_{IN+} < V_{IN-}$
0 = $V_{IN+} > V_{IN-}$

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits
11 = Trigger/event/interrupt is generated on any change of the comparator output (while CEVT = 0)
10 = Trigger/event/interrupt is generated on the transition of the comparator output:
If CPOL = 0 (non-inverted polarity):
High-to-low transition only.
If CPOL = 1 (inverted polarity):
Low-to-high transition only.
01 = Trigger/event/interrupt is generated on the transition of the comparator output
If CPOL = 0 (non-inverted polarity):
Low-to-high transition only.
If CPOL = 1 (inverted polarity):
High-to-low transition only.
00 = Trigger/event/interrupt generation is disabled

bit 5 **Unimplemented:** Read as ‘0’

If the WDT is enabled in hardware (FWDTEN<1:0> = `11`), it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake and code execution will continue from where the `PWRSAV` instruction was executed. The corresponding SLEEP or IDLE bit (RCON<3:2>) will need to be cleared in software after the device wakes up.

The WDT Flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

Note:	The `CLRWDT` and `PWRSAV` instructions clear the prescaler and postscaler counts when executed.

26.3.1 WINDOWED OPERATION

The Watchdog Timer has an optional Fixed Window mode of operation. In this Windowed mode, `CLRWDT` instructions can only reset the WDT during the last 1/4 of the programmed WDT period. A `CLRWDT` instruction executed before that window causes a WDT Reset, similar to a WDT time-out.

Windowed WDT mode is enabled by programming the Configuration bit, WINDIS (FWDT<6>), to '`0`'.

26.3.2 CONTROL REGISTER

The WDT is enabled or disabled by the FWDTEN<1:0> Configuration bits. When both the FWDTEN<1:0> Configuration bits are set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN<1:0> Configuration bits have been programmed to '`10`'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user to enable the WDT for critical code segments, and disable the WDT during non-critical segments, for maximum power savings. When the FWTEN<1:0> bits are set to '`01`', the WDT is only enabled in Run and Idle modes, and is disabled in Sleep. Software control of the SWDTEN bit (RCON<5>) is disabled with this setting.

FIGURE 26-2: WDT BLOCK DIAGRAM

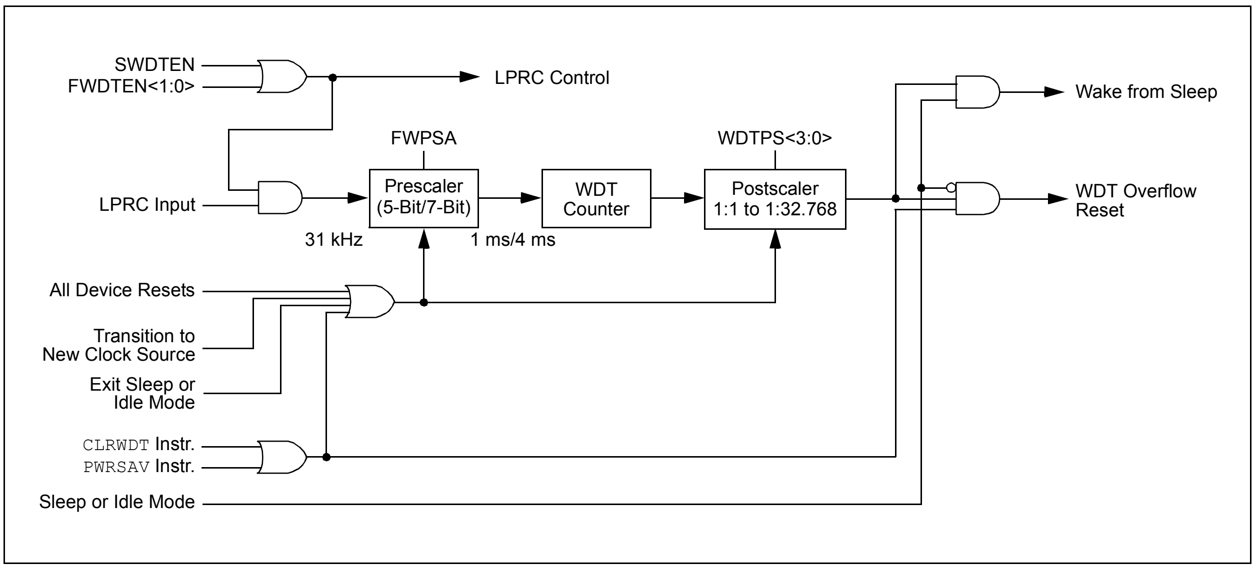


FIGURE 29-8: TIMER1/2/3/4/5 EXTERNAL CLOCK INPUT TIMING

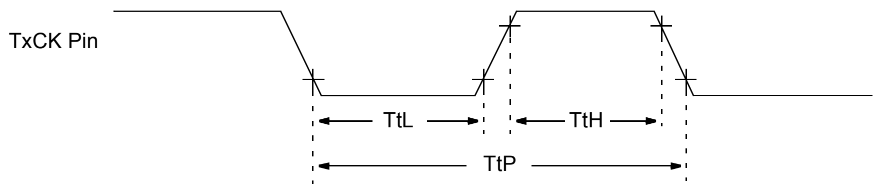


TABLE 29-27: TIMER1/2/3/4/5 EXTERNAL CLOCK INPUT REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
	TtH	TxCK High Pulse Time	Sync w/Prescaler	TCY + 20	—	ns	Must also meet Parameter Ttp
			Async w/Prescaler	10	—	ns	
			Async Counter	20	—	ns	
	TtL	TxCK Low Pulse Time	Sync w/Prescaler	TCY + 20	—	ns	Must also meet Parameter Ttp
			Async w/Prescaler	10	—	ns	
			Async Counter	20	—	ns	
	TtP	TxCK External Input Period	Sync w/Prescaler	2 * TCY + 40	—	ns	N = Prescale Value (1, 4, 8, 16)
			Async w/Prescaler	Greater of: 20 or (2 * TCY + 40)/N	—	ns	
			Async Counter	40	—	ns	
		Delay for Input Edge to Timer Increment	Synchronous	1	2	TCY	
			Asynchronous	—	20	ns	

FIGURE 29-9: INPUT CAPTURE x TIMINGS

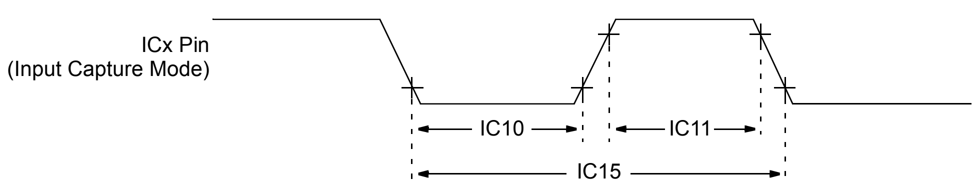


TABLE 29-28: INPUT CAPTURE x REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
IC10	TccL	ICx Input Low Time – Synchronous Timer	No Prescaler	TCY + 20	—	ns	Must also meet Parameter IC15
			With Prescaler	20	—	ns	
IC11	TccH	ICx Input Low Time – Synchronous Timer	No Prescaler	TCY + 20	—	ns	Must also meet Parameter IC15
			With Prescaler	20	—	ns	
IC15	TccP	ICx Input Period – Synchronous Timer		(2 * TCY + 40)/N	—	ns	N = prescale value (1, 4, 16)

FIGURE 30-32: TYPICAL BAND GAP VOLTAGE vs. VDD

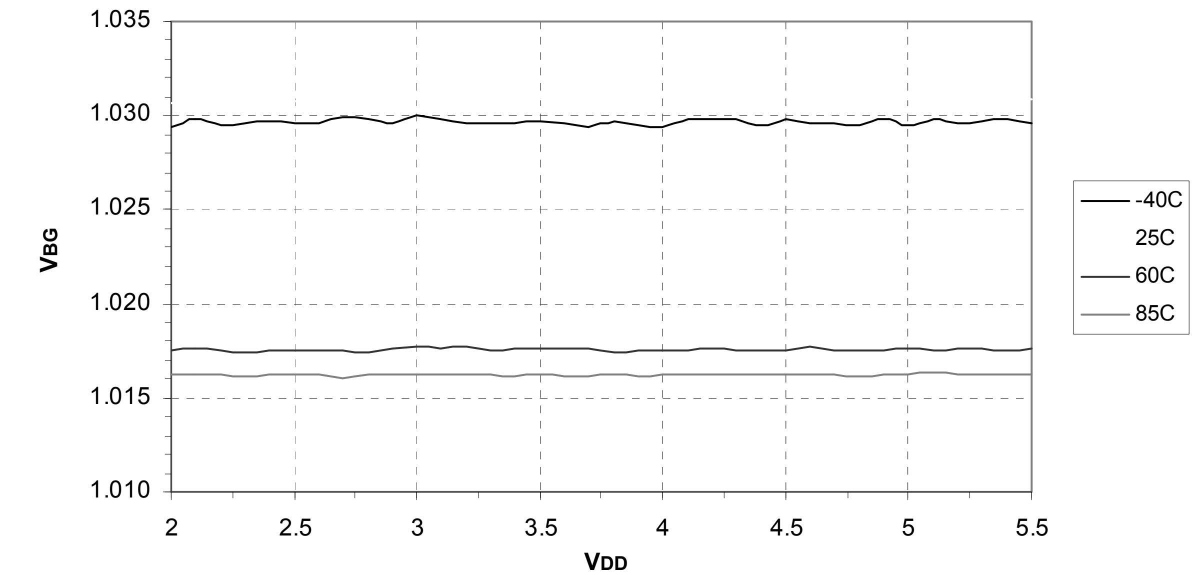


FIGURE 30-33: TYPICAL BAND GAP VOLTAGE vs. TEMPERATURE (2.0V ≤ VDD ≤ 5.5V)

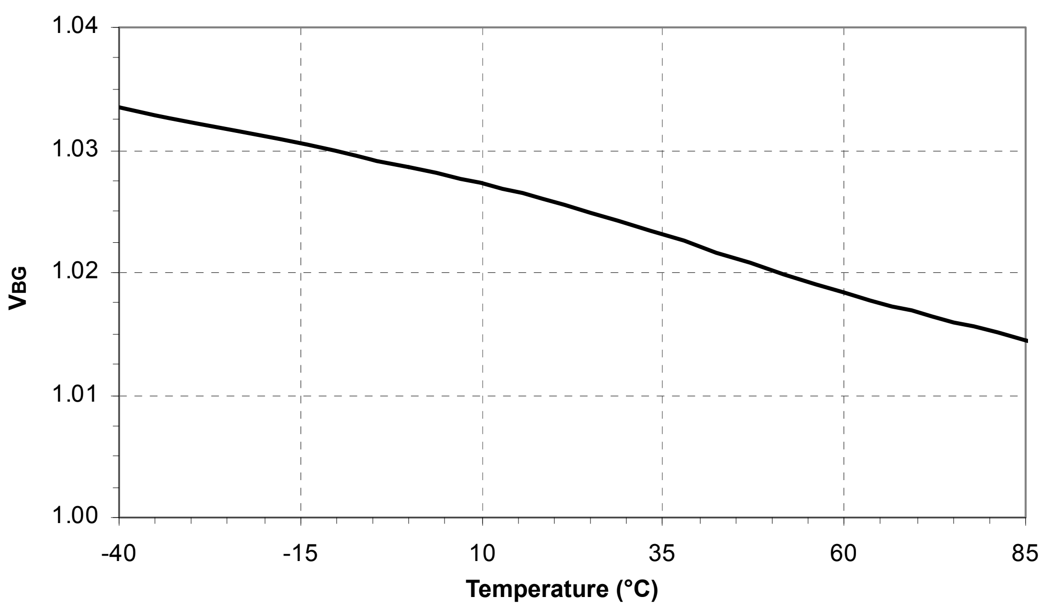


FIGURE 30-55: TYPICAL BAND GAP VOLTAGE vs. TEMPERATURE (2.0V $\leq$ V_{DD} $\leq$ 5.5V)

V_{BG} (V)

Temperature (°C)

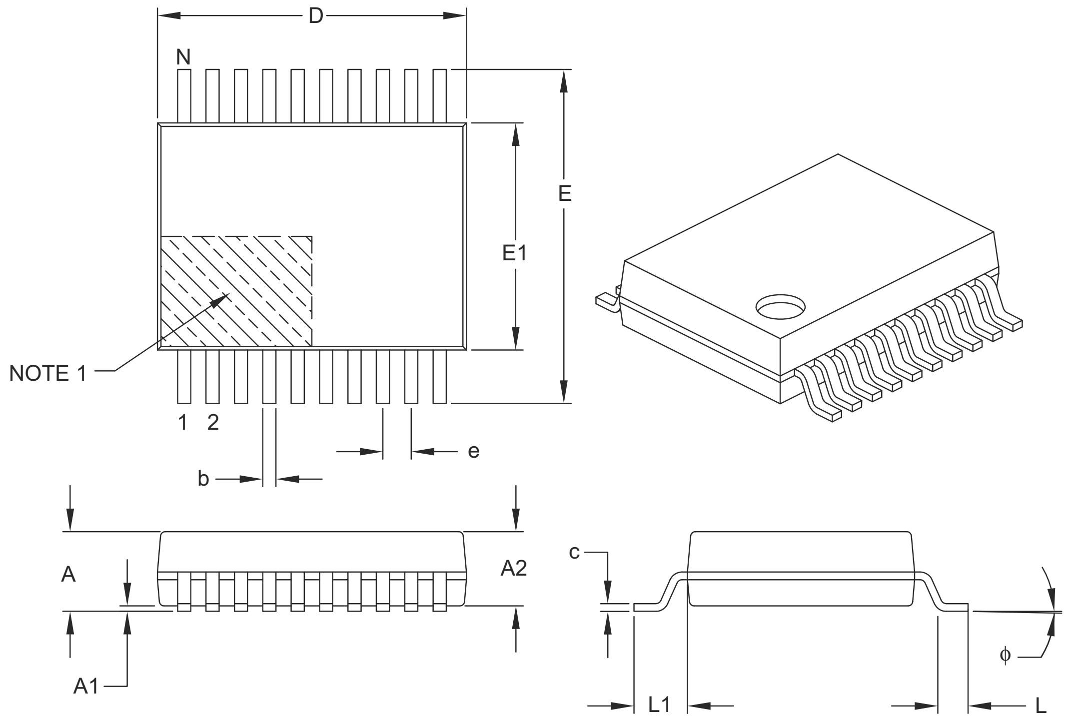
FIGURE 30-56: TYPICAL VOLTAGE REGULATOR OUTPUT vs. TEMPERATURE

Regulator Output (V)

Temperature (°C)

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	20		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

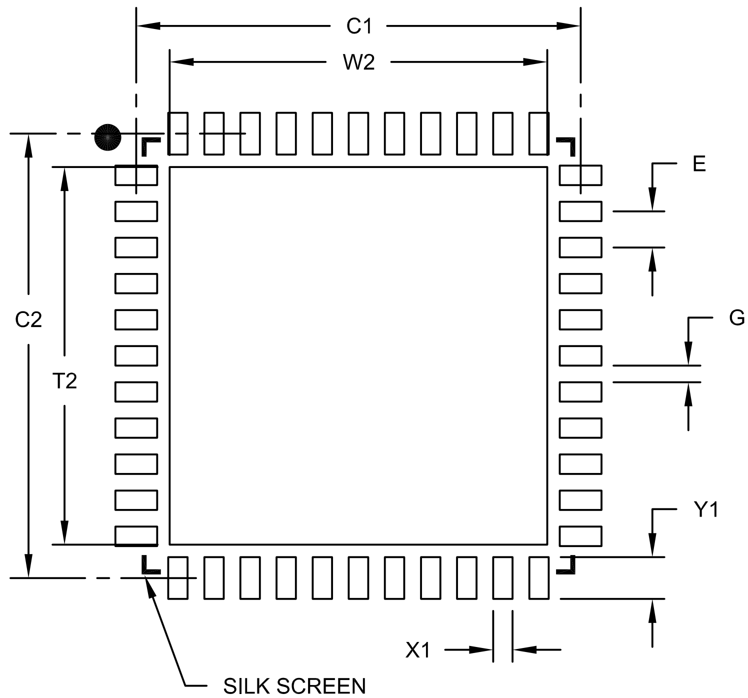
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			6.60
Optional Center Pad Length	T2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

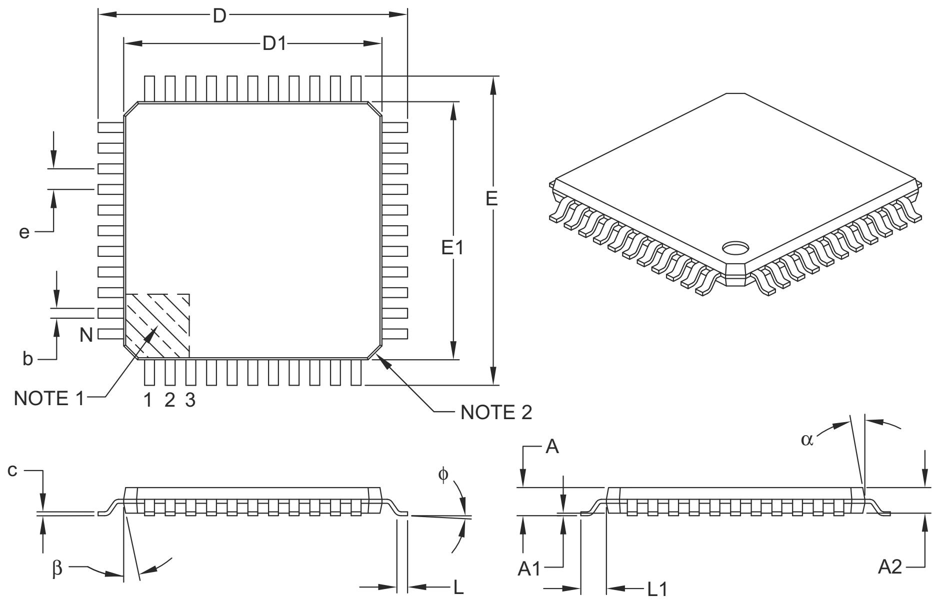
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103B

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Leads	N	44		
Lead Pitch	e	0.80 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

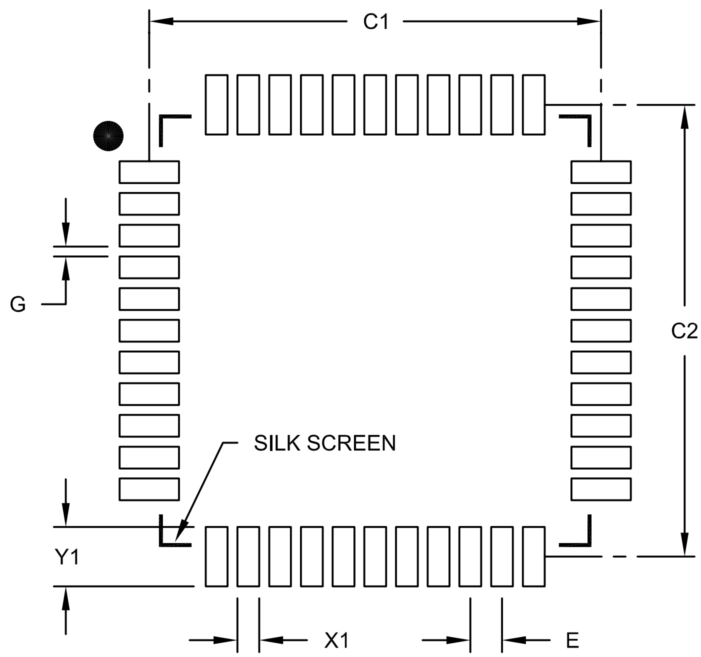
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
	Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.80 BSC		
Contact Pad Spacing	C1			11.40	
Contact Pad Spacing	C2			11.40	
Contact Pad Width (X44)	X1				0.55
Contact Pad Length (X44)	Y1				1.50
Distance Between Pads	G		0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

NOTES: